



CICTA

Centro de Investigación en Ciencia y Tecnología Aplicada

Transforming research and education in Mexico with advanced technology



CIETa
Centro de Investigación
en Ciencia y Tecnología Aplicada

CENAM
CENTRO NACIONAL DE METROLOGÍA

Centro de Física Aplicada y Tecnología Avanzada

IEEE
MEMS 2011
Cancun Mexico
January 23-27, 2011

**REINFORCEMENT OF MEMS
R&D IN MEXICO**

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Six leading Mexican research and academic institutions have initiated a national collaborative program to establish a well-structured basis for MEMS research in Mexico, utilizing common design and analysis software-platforms, and sharing the available processing infrastructure.

The program is based on a little exercised paradigm within Mexican researchers/educators: sharing infrastructure and resources dedicated for research and development among Mexican institutions, so as to strengthen activities targeted towards MEMS fabrication and testing.

The project is funded by the National Council of Science and Technology (CONACyT) in Mexico, and the main objectives are as follows:

- a) Training of personnel (researchers and students) on MEMS design using Sandia Labs' Advanced MEMS Design Tools.
- b) Establishment of a MEMS research network focused on design, analysis and fabrication of MEMS structures in Mexico.
- c) Organization of a MEMS Design Competition to promote active participation of students in MEMS-technology issues; it is expected to be held each year.
- d) To identify and promote collaboration between industry and academia.
- e) To promote collaboration among Mexican and Sandia National Laboratories' researchers.

CONACYT

Sandia National Laboratories

Initiation of MEMS Technology in Mexico

- Formal MEMS-Education in UG & G programs
- Identification of (AI) Academy-Industry teams
- Initiation of AI-projects to be addressed with SUMMIT-Sandia's Technology
- Fabrication of MUA-modules. Research /AI
- Identification Focus-Areas for MEMS research -RFMEMS, BiOMEMS, Sensors
- Perform complete testing cycles of MEMS
- Packaging of MEMS devices - assessments

5-year program:

- 2010
- 2011
- 2012
- 2013-2014

- 2nd MUA Competition & Fabrication of modules
- Expansion of AI-teams
- Expansion of AI-projects to be addressed with SUMMIT-Sandia's Technology
- Fabrication of MUA-modules. Research- and AI-projects
- Acquisition of further infrastructure for MEMS process development
- Development/identification of alternative processes to SUMMIT-V
- MEMS Workshops/Colloquia
- Formulation of extended AERI-MEMS projects
- Application-driven projects
- Development/Identification of MEMS Embedded Systems Integration
- MEMS-CMOS Design Centers / MEMS Network
- Commercial MEMS Manufacturing in Mexico
- Expanding collaboration with Sandia – LIGA Nanotechnology Joint Research/Projects

National Projects (FORDECYT Conacyt)

- Project title “**Establecimiento de un Programa Nacional para el Diseño y Fabricación de Prototipos MEMS (Micro-Electro-Mechanical Systems)**”,
- Total funded \$22M pesos, ~€1.3M
- Collaboration with institutions:
 - Centro Nacional de Metrología (CENAM, Querétaro QRO),
 - Universidad Autónoma de Ciudad Juárez,
 - Instituto Politécnico Nacional (IPN, México DF),
 - Instituto Nacional de Astrología, Óptica y Electrónica (INAOE, Puebla),
 - Universidad Veracruzana (UV, Xalapa VER),
 - Centro de Física Aplicada y Tecnología Avanzada (CFATA-UNAM - Campus Juriquilla, Querétaro, QRO.)



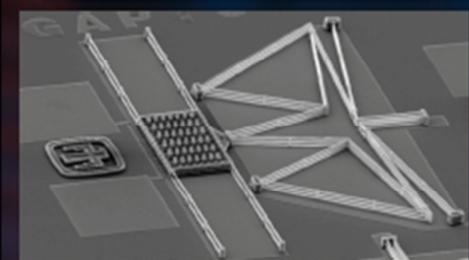
FORDECyT project started 2010



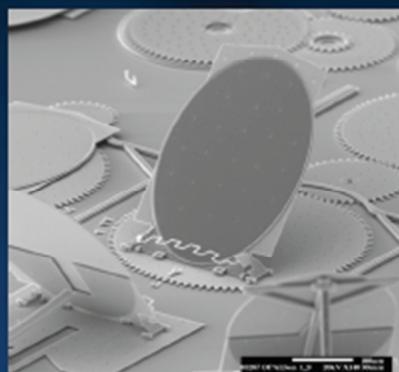
Training Super-Users in Sandia by 2009



Summit-V process from Sandia NL

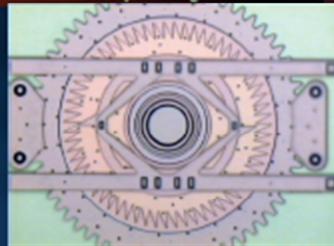


Compliant Displacement Multiplier Mechanism

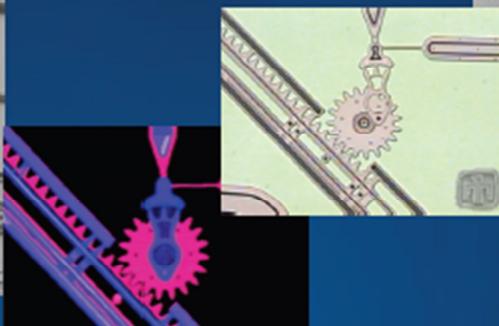


Erected Mirror on a Rotary Stage

Rotary Indexing Actuator



Optical Programmable Array Logic



Pop-up Mirror, 1996

CICTA's Infrastructure in MEMS Technology

Lab. Packaging and test

Design of MEMS



Lab. Electronic Microscopy



New 6" line manufacturing equipment for MEMS packaging

Suss MicroTec

FC150

Flip chip bonder
Die-wafer Bonder
Optoelectronic assy
Photonics assy



(UACJ)

Disco High Tec

DAD 3220

Disco wafer dicing
for up to 6" wafers



Suss MicroTec

BA6

Aligner
for 2" – 6" wafers



Suss MicroTec

SB6e

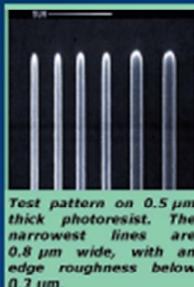
Wafer-wafer Bonder
Anodic Bonder
Eutectic Bonder
Fusion Bonder
Thermo compression



CICTA's Pending Infrastructure (to arrive by Summer 2010)



Microtech's LaserWriter LW405



Test pattern on 0.5 μm thick photoresist. The narrowest lines are 0.8 μm wide, with an edge roughness below 0.2 μm .



Detail of a grey-level LDW mask for Diffractive Optics. The pixel size is 2 \times 2 μm .



Microlens array obtained by grey-level exposure on photoresist. Each lens is 60 μm wide and 5 μm thick.

0.8, 2 or 4 μm linewidth



Centro de Investigación en Ciencia y Tecnología Aplicada, April 27, 2011



Infraestructure at INAOE, Puebla

Started in 1974.

fabricación de Circuitos Integrados (CIs)
Bipolar, NMOS & CMOS

10 um from 1974 - 2008

BiCMOS 0.8 um started 2009

SERVICIOS TECNOLÓGICOS

- Diseño de Circuitos Integrados
- Diseño de MEMS
- Diseño y Fabricación de Mascarillas
- Fabricación de prototipos de MEMS
- Fabricación de Circuitos Integrados
- Caracterización Funcional de MEMS a nivel oblea
- Centro de Entrenamiento:
Tecnología de Microelectrónica
MEMS

 Centro de Investigación en Ciencia y Tecnología

INSTITUTO NACIONAL DE ASTROFÍSICA, ÓPTICA Y ELECTRÓNICA

LABORATORIO DE INNOVACIÓN EN MEMS

INAUGURACIÓN 19 ABRIL 2010



Se tiene el objetivo de consolidar una infraestructura de fabricación en alta tecnología que aglutine a los científicos del país y dirigirlos con un enfoque multidisciplinario hacia la investigación e innovación en tecnología de Nanoelectrónica y MEMS/NEMS.
Establecer una plataforma tecnológica que dé soporte a la formación de recursos humanos altamente calificados e impulse el desarrollo de la industria electrónica nacional.

CARACTERÍSTICAS

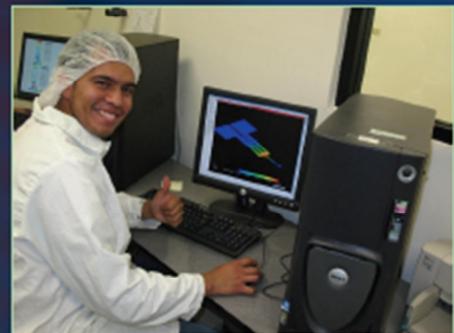
- 600 m² de sala clase 10 y 100
- Equipo de fabricación con óptica de 6 pulgadas
- Desarrollo de un proceso BiCMOS de 0.8 um
- Fabricación de sensores, actuadores y MEMS
- Microensamblado Superficie y de Volumen
- Aplicaciones analógicas y digitales
- Dispositivos IBT de heteroestructura
- Materiales Nanoestructurados

MINI COLOQUIO 19 - 20 ABRIL

- Dr. Jamal Deen**
McMASTER UNIVERSITY, CANADA
- Dr. Cor L. Claeyns**
IMEC, BÉLGICA
- Dr. Fernando Guarín**
IBM MICROELECTRONICS, EUA
- Dr. Subramanian S. Iyer**
IBM MICROELECTRONICS, EUA
- Dr. Rafael Ríos**
INTEL, EUA

Thank you!



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**Head of the Applied Science and Technology Research Center
(CICTA)**

Research Professor

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